

Title (en)

HIGH-STRENGTH SOFT-MAGNETIC COMPOSITE MATERIAL OBTAINED BY COMPACTION/BURNING AND PROCESS FOR PRODUCING THE SAME

Title (de)

HOCHBELASTBARES WEICHMAGNETISCHES VERBUNDMATERIAL, DAS DURCH KOMPAKTIERUNG/BRENNUNG ERHALTEN WIRD, UND PROZESS ZU SEINER HERSTELLUNG

Title (fr)

MATÉRIAU COMPOSITE MAGNÉTIQUE DOUX À HAUTE RÉSISTANCE OBTENU PAR COMPACTION/COMBUSTION ET SON PROCÉDÉ DE FABRICATION

Publication

**EP 2219195 A4 20160803 (EN)**

Application

**EP 08847585 A 20081106**

Priority

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- JP 2007289774 A 20071107

Abstract (en)

[origin: EP2219195A1] The present invention relates to a soft-magnetic composite material obtained by compaction and heat treatment. This material is produced by mixing and compacting Mg-containing oxide-coated soft-magnetic particles with at least one type of silicone resin, low melting glass and metal oxide, and heat treatment in a non-oxidizing atmosphere to obtain a precursor of a soft-magnetic composite compaction-heat treated material, followed by heat-treating in an oxidizing atmosphere to obtain a heat treated body.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [X] WO 2007004727 A1 20070111 - MITSUBISHI STEEL MFG [JP], et al
- [A] JP 2006332524 A 20061207 - MITSUBISHI MATERIALS PMG CORP
- [A] JP 2000232014 A 20000822 - MATSUSHITA ELECTRIC IND CO LTD
- See references of WO 2009060895A1

Cited by

EP3693101A4; EP2680281A4; EP3441989A4; US9318244B2; US9805855B2; US11183321B2

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